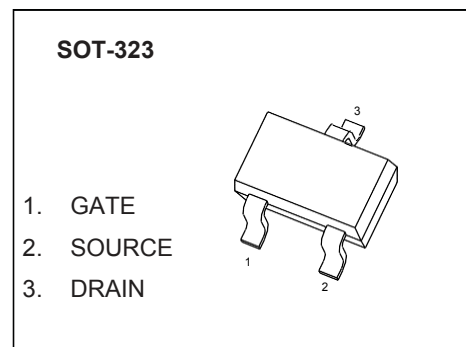


## Plastic-Encapsulate MOSFETS

### N-Channel MOSFET

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	$I_D$
60 V	5K@10V	340mA
	5.3K@4.5V	



### FEATURE

- z Highdensity cell design for Low  $R_{DS(on)}$
- z Voltagecontrolled smallsignal switch
- z Rugged andreliable
- z High saturation current capability
- z ESD protected

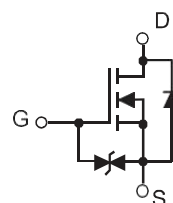
### APPLICATION

- Load Switch for Portable Devices
- DC/DC Converter

### MARKING



### Equivalent Circuit



### MOSFET MAXIMUM RATINGS ( $T_a=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	340	mA
$I_{DM}$	Pulsed Drain Current(note 1)	800	mA
$P_D$	Power Dissipation	0.2	W
$T_j$	Junction Temperature	150	$^\circ\text{C}$
$T_{stg}$	Storage Temperature	-55~+150	$^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient	625	$^\circ\text{C/W}$

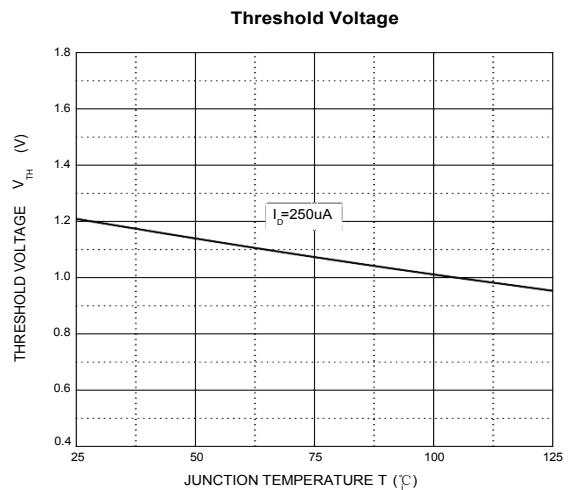
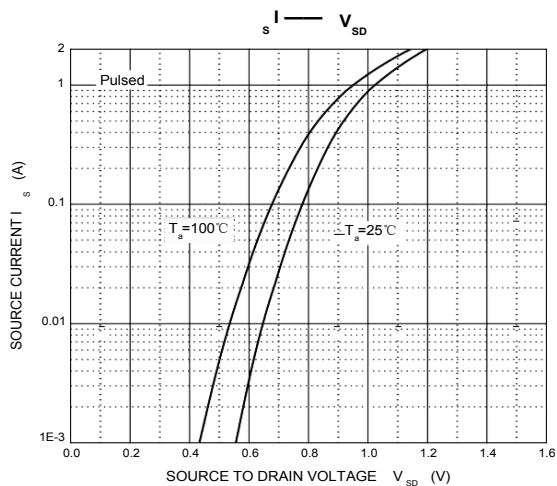
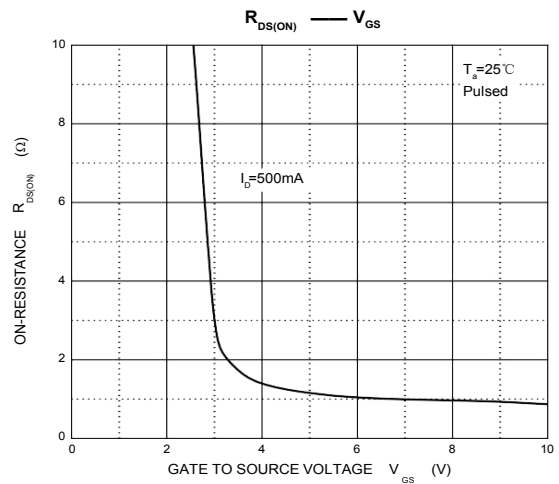
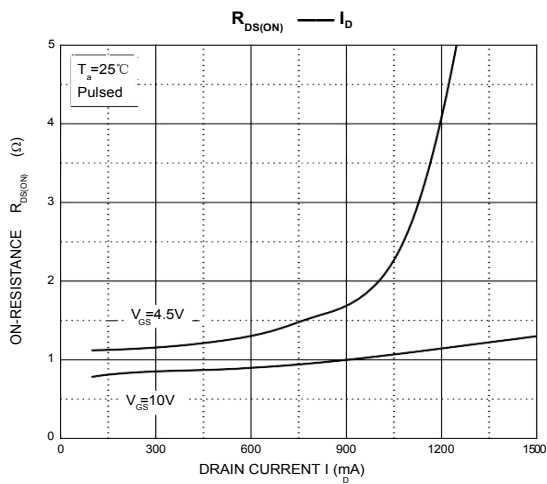
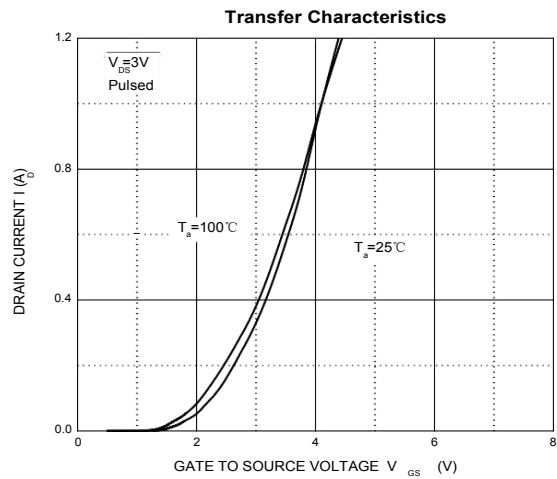
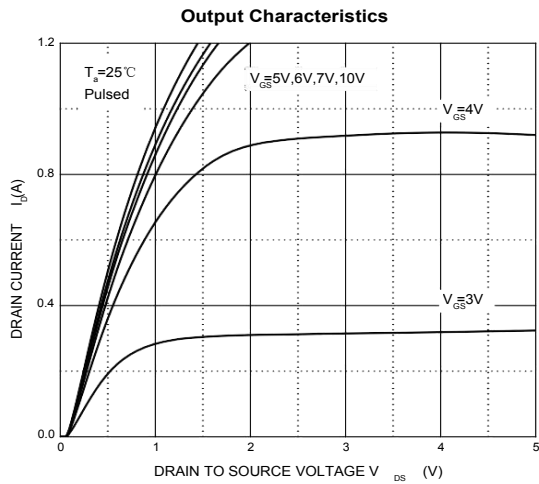
**MOSFET ELECTRICAL CHARACTERISTICS**
**T<sub>a</sub>=25 °C unless otherwise specified**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>STATIC PARAMETERS</b>						
Drain-source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	60			V
GateThreshold Voltage (note 2)	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 1mA	1	1.3	2.5	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 48V, V <sub>GS</sub> = 0V			1	μA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			±10	μA
Drain-Source On-Resistance (note 2)	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 200mA		1.1	5.3	Ω
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 500mA		0.9	5	Ω
<b>DYNAMIC PARAMETERS (note 3)</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 0V, f = 1MHz			40	pF
Output Capacitance	C <sub>oss</sub>				30	pF
Reverse Transfer Capacitance	C <sub>rss</sub>				10	pF
<b>SWITCHING PARAMETERS (note 3)</b>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>GS</sub> = 10V, V <sub>DD</sub> = 50V, R <sub>G</sub> = 50Ω			10	ns
Turn-off Delay Time	t <sub>d(off)</sub>	R <sub>GS</sub> = 50Ω, R <sub>L</sub> = 250Ω			15	ns
Reverse Recovery Time	t <sub>rr</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = 300mA, V <sub>R</sub> = 25V, dI <sub>S</sub> /dt = -100A/μs		30		ns
Recovered Charge	Q <sub>r</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = 300mA, V <sub>R</sub> = 25V, dI <sub>S</sub> /dt = -100A/μs		30		nC
<b>GATE-SOURCE ZENER DIODE</b>						
Gate-Source Breakdown Voltage	BV <sub>GSO</sub>	I <sub>GS</sub> = 1mA (Open Drain)	21.5		30	V
<b>DRAIN-SOURCE DIODE</b>						
Diode Forward Voltage (note 2)	V <sub>SD</sub>	I <sub>S</sub> = 300mA, V <sub>GS</sub> = 0V			1.5	V
Continuous Diode Forward Current	I <sub>S</sub>				0.2	A
Pulsed Diode Forward Current (note 1)	I <sub>SM</sub>				0.53	A

**Notes :**

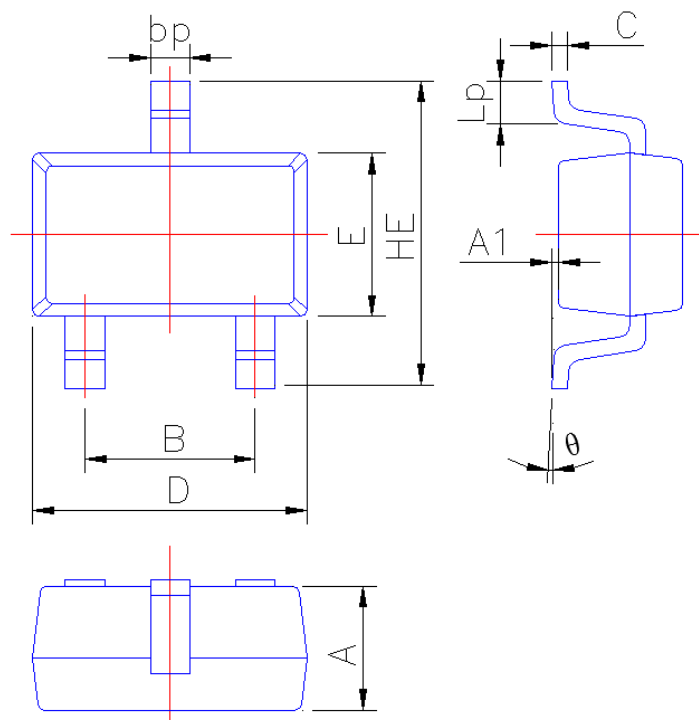
1. Repetitive rating + Pulse width limited by junction temperature.
2. Pulse Test : Pulse width > 300μs, duty cycle > 2%.
3. Guaranteed by design, not subject to production testing.

## Typical Characteristics



**PACKAGE OUTLINE**

Plastic surface mounted package; 3 leads

**SOT-323**


Symbol	Dimension in Millimeters	
	Min	Max
A	0.90	1.00
A1	0.010	0.100
B	1.20	1.40
bp	0.25	0.45
C	0.09	0.15
D	2.00	2.20
E	1.15	1.35
HE	2.15	2.55
Lp	0.25	0.46
$\theta$	0°	6°